SEMICONDUCTOR

TECHNICAL DATA

TOSHIBA FIELD EFFECT TRANSISTOR

Y T F 8 3 0

SILICON N CHANNEL MOS TYPE

(π-MOS II)

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS.

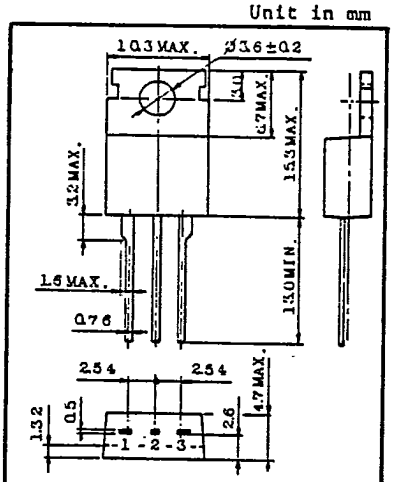
CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS.

INDUSTRIAL APPLICATIONS

FEATURES:

- Low Drain-Source ON Resistance : $R_{DS(ON)}$=1.3Ω (Typ.)
- High Forward Transfer Admittance : $|Yfs|$=3.25S (Typ.)
- Low Leakage Current : I_{GSS}=±500nA(Max.) @ V_{GS}=±20V
  I_{DSS}= 250μA(Max.) @ V_{DS}=500V
- Enhancement-Mode : V_{th}=2.0~4.0V @ V_{DS}=V_{GS}, I_D=250μA

Unit in mm



JEDEC	TO-220AB
EIAJ	SC-46
TOSHIBA	2-10A3B

Weight : 1.9g

MAXIMUM RATINGS (Ta=25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSX}	500	V
Drain-Gate Voltage (R_{GS}=1MΩ)		V_{DGR}	500	V
Gate-Source Voltage		V_{GSS}	±20	V
Drain Current	DC(Tc=25°C)	I_D	4.5	A
	DC(Tc=100°C)	I_D	3	
	Pulse	I_{DP}	18	
Inductive Current (Clamped)		I_{LP}	18	A
Drain Power Dissipation (Tc=25°C)		P_D	75	W
Channel Temperature		T_{ch}	150	°C
Storage Temperature Range		T_{stg}	-55~150	°C

THERMAL CHARACTERISTICS

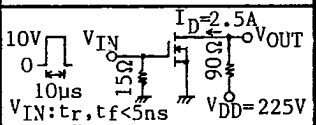
CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Junction to Case	Rth(j-c)	1.67	°C/W
Thermal Resistance, Junction to Ambient	Rth(j-a)	80	°C/W
Muximum Lead Temperature for Soldering Purposes (1.6mm from case for 10 seconds)	T_L	300	°C

SEMICONDUCTOR

TECHNICAL DATA

YTF830

ELECTRICAL CHARACTERISTICS (Ta=25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I_{GSS}	V_{GS}=±20V, V_{DS}=0V	–	–	±500	nA
Drain Cut-off Current		I_{DSS}	V_{DS}=500V, V_{GS}=0V, Tc=25°C	–	–	250	μA
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	I_D=250μA, V_{GS}=0V	500	–	–	V
Gate Threshold Voltage		V_{th}	V_{DS}=V_{GS}, I_D=250μA	2.0	–	4.0	V
Forward Transfer Admittance		$\|Yfs\|$	V_{DS}=10V, I_D=2.5A	2.5	3.25	–	S
On-State Drain Current		$I_{D(ON)}$	V_{DS}=10V, V_{GS}=10V	4.5	–	–	A
Drain-Source ON Resistance		$R_{DS(ON)}$	I_D=2.5A, V_{GS}=10V	–	1.3	1.5	Ω
Drain-Source ON Voltage		$V_{DS(ON)}$	I_D=4.5A, V_{GS}=10V	–	6.4	8.7	V
Input Capacitance		C_{iss}	V_{DS}=25V, V_{GS}=0V, f=1MHz	–	600	800	pF
Reverse Transfer Capacitance		C_{rss}		–	40	60	pF
Output Capacitance		C_{oss}		–	150	200	pF
Switching Time	Rise Time	t_r		–	15	30	ns
	Turn-on Time	t_{on}		–	30	60	ns
	Fall Time	t_f		–	15	30	ns
	Turn-off Time	t_{off}		–	40	85	ns
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q_g	V_{GS}=10V, I_D=6A, V_{DS}=400V	–	22	30	nC
Gate Source Charge		Q_{gs}		–	11	–	nC
Gate-Drain ("Miller") Charge		Q_{gd}		–	11	–	nC

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta=25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Source Current	I_S	—	–	–	4.5	A
Pulse Source Current	I_{SP}	—	–	–	18	A
Diode Forward Voltage	V_{SD}	I_S=4.5A, V_{GS}=0V, Tc=25°C	–	–	1.6	V
Reverse Recovery Time	t_{rr}	Tj=150°C, I_F=4.5A, dI_F/dt=100A/μs	–	800	–	ns
Reverse Recovered Charge	Q_{rr}		–	4.6	–	μC